L Number	Hits	Search Text	DB	Time stamp
-	42	"thinned chip" or "thinned chips"	USPAT;	2003/12/31
			US-PGPUB;	17:56
			EPO; JPO;	
			DERWENT;	•
_	2	5268065.pn.	USPAT;	2003/10/24
			US-PGPUB;	14:49
			EPO; JPO;	
			DERWENT; IBM TDB	
-	10	"824301"	USPAT;	2003/10/24
			US-PGPUB;	15:17
			EPO; JPO; DERWENT;	
			IBM TDB	
-	3964	"smart card" and chip\$1	USPAT;	2003/10/24
			US-PGPUB; EPO; JPO;	14:14
	İ		DERWENT;	
	1.607	,,	IBM_TDB	
_	1607	"smart card" with chip\$1	USPAT;	2003/10/24
			US-PGPUB; EPO; JPO;	14:28
			DERWENT;	
_	189	("smart card" with chip\$1).ti.	IBM_TDB	
	103	/ Small card with chipsi).ti.	USPAT; US-PGPUB;	2003/10/24
			EPO; JPO;	11.29
			DERWENT;	
_	13	("4511796" "4714980" "4789776"	IBM_TDB USPAT	2002/10/24
		"4822988" "4825283" "5048179"	USPAI	2003/10/24 14:40
		"5049728" "5081520" "5155068"		
		"5526233" "5703755" "5965867" "5991159").PN.		
-	13	("4511796" "4714980" "4789776"	USPAT	2003/10/24
		"4822988" "4825283" "5048179"		14:48
		"5049728" "5081520" "5155068" "5526233" "5703755" "5965867"		
		"5991159").PN.		
-	2	5192682.pn.	USPAT;	2003/10/24
			US-PGPUB;	14:50
•			EPO; JPO; DERWENT;	
			IBM TDB	
-	2	6137687.pn.	USPĀT;	2003/10/24
			US-PGPUB; EPO; JPO;	15:18
			DERWENT;	
_	13	/!! 45.11706!! !! 477.4000!! !! 5000	IBM_TDB	
	13	("4511796" "4714980" "4789776" "4822988" "4825283" "5048179"	USPAT	2003/10/24
		"5049728" "5081520" "5155068"		15:23
		"5526233" "5703755" "5965867"		
_	46	"5991159").PN. 4511796.URPN.	IICDAM	2002/10/64
			USPAT	2003/10/24 15:29
_	225	("chip card" or "chip cards").ti.	USPAT	2003/10/24
_	1	5122481.pn.	IIGDAM	16:19
	_	<u>-</u>	USPAT	2003/11/14 14:18
-	141	lintec.as.	USPAT	2003/11/14
_	30	lintec.as. and 156/\$.ccls.	Haban	13:32
		·	USPAT	2003/11/14 13:33
-	2996	156/344 or 156/584	USPAT	2003/11/14
_	109	(156/344 or 156/584) and (dissolv\$3 with	Hans-	13:33
		(adhesive or glue))	USPAT	2003/11/14 13:34
			L	TO . O 3

	42	(adhesive or glue)) and (semiconductor\$1	USPAT	2003/11/14 13:36
_	8	or wafer\$1) (156/344 or 156/584) and (dissolv\$3 with (adhesive or glue)) and (semiconductor\$1	USPAT	2003/11/14 14:07
_	35	or wafer\$1) and dic\$3	USPAT	2003/11/14
			OSPAI	14:03
=	109	(dissolv\$3 with (adhesive or glue)) and (semiconductor\$1 or wafer\$1) and dic\$3	USPAT	2003/11/14 14:42
_	7	(dissolv\$3 with (adhesive or glue)) and	USOCR	2003/11/14
_	3	(semiconductor\$1 or wafer\$1) and dic\$3	USPAT;	14:11 2003/11/14
			US-PGPUB;	14:21
			EPO; JPO; DERWENT;	
_	14	(wafer\$1 with thinning) with ((dicing or	IBM_TDB	2002/11/14
		separating) with (chip\$1))	USPAT	2003/11/14 14:26
_	7	<pre>(wafer\$1 with thinning) with ((dicing or separating) with (chip\$1))</pre>	EPO; JPO; DERWENT;	2003/11/14 14:26
		_	IBM_TDB	
_	537	438/464	USPAT	2003/11/14 14:43
-	24	438/464 and (dissolv\$3 with (adhesive or glue))	USPAT	2003/11/14
-	5	438/464 and (dissolv\$3 with (adhesive or	USOCR	14:47 2003/11/14
_	17646	glue)) card with chip	USPAT;	14:47
	1,010	outa with only	US-PGPUB;	17:56
			EPO; JPO; DERWENT;	
_	5109	(gand with whip with (singuite)	IBM_TDB	
	3109	(card with chip with (circuit\$2 or conductive))	USPAT; US-PGPUB;	2003/12/31 17:57
			EPO; JPO; DERWENT;	
	1.1		IBM_TDB	
-	11	card with chip with conductive with path	USPAT; US-PGPUB;	2003/12/31 18:01
			EPO; JPO;	
			DERWENT; IBM TDB	
-	0	card with "thinned chip"	USPAT;	2003/12/31
			US-PGPUB; EPO; JPO;	18:01
			DERWENT; IBM TDB	
-	15	card with thinned with chip\$1	USPAT;	2003/12/31
			US-PGPUB; EPO; JPO;	18:01
			DERWENT;	
-	7	"thinned chip"	IBM_TDB USPAT	2003/12/31
_	17	"thinned chip"	USPAT;	18:07 2003/12/31
	·	•	US-PGPUB;	18:11
			EPO; JPO; DERWENT;	
_	558	(156/\$.ccls. or 235/\$.ccls.) and (chip\$1	IBM_TDB	2002/10/21
		with thin\$4)	USPAT; US-PGPUB;	2003/12/31 18:12
	ļ		EPO; JPO; DERWENT;	
	145	/156/6 gala on 225/61- \	IBM_TDB	
	143	(156/\$.ccls. or 235/\$.ccls.) and (chip\$1 near2 thin\$4)	USPAT; US-PGPUB;	2003/12/31 18:15
			EPO; JPO; DERWENT;	
			IBM_TDB	

-	62	(USPAT;	2003/12/31
		near2 thin\$4) and card\$1	US-PGPUB;	18:22
			EPO; JPO;	1
			DERWENT;	
1_	14594	print\$3 with coil	IBM_TDB USPAT;	2002/12/21
	14354	princes with corr	US-PGPUB;	2003/12/31 18:23
			EPO; JPO;	10.23
i		1	DERWENT;	
			IBM TDB	
-	1147	11 (USPAT;	2003/12/31
		conductive)	US-PGPUB;	18:23
			EPO; JPO;	
			DERWENT; IBM TDB	
-	72	(print\$3 near4 (coil near1 (inductive or	USPAT;	2003/12/31
		conductive)))	US-PGPUB;	18:27
	į		EPO; JPO;	20121
İ			DERWENT;	
	2400	456/044	IBM_TDB	
-	3420	156/344 or 156/584	USPAT;	2003/12/31
			US-PGPUB;	18:27
1			EPO; JPO; DERWENT;	
			IBM TDB	
-	394	(156/344 or 156/584) and chip\$1	USPAT;	2003/12/31
			US-PGPUB;	18:27
			EPO; JPO;	
			DERWENT;	
_	24	/156/244 on 156/504) and all 441	IBM_TDB	
	24	(156/344 or 156/584) and chip\$1 and (dissolv\$3 with adhesive)	USPAT;	2003/12/31
		(dissolvas with addresive)	US-PGPUB; EPO; JPO;	18:33
	1		DERWENT;	
			IBM TDB	
-	1487	156/344.ccls.	USPAT;	2003/12/31
	Ì		US-PGPUB;	18:34
			EPO; JPO;	
	1 .		DERWENT;	'
_	1216	156/344.ccls.	IBM_TDB	
	1210	1307544.0015.	USPAT	2003/12/31
_	438	156/344.ccls. and (adhesive with (double	USPAT	18:37 2003/12/31
		or two or "2" or second))		18:37
-	2	stromberg with michael	USPAT;	2004/03/18
			US-PGPUB;	22:52
	1		EPO; JPO;	
			DERWENT;	
_	2062	wafer\$1 with thin\$3 with (divid\$3 or	IBM_TDB	2004/02/10
		separat\$3 or dic\$3)	USPAT; US-PGPUB;	2004/03/18 22:53
		· · · - · · - · · · · · · · · · · · · ·	EPO; JPO;	22.33
			DERWENT;	
			IBM_TDB	
_	1673	wafer\$1 with thin\$3 with (divid\$3 or	USPĀT;	2004/03/18
		separat\$3 or dic\$3)	EPO; JPO;	22:55
			DERWENT;	
_	521	(wafer\$1 with thin\$3 with (divid\$3 or	IBM_TDB	2004/02/10
İ	""	separat\$3 or dic\$3)).ab.	USPAT; EPO; JPO;	2004/03/18 22:59
]		DERWENT;	44.33
			IBM TDB	
_	28	5268065.URPN.	USPAT	2004/03/18
_		/ £ 6.1		22:57
_	89	(wafer\$1 with thin\$3 with (divid\$3 or	USPAT;	2004/03/18
		separat\$3 or dic\$3)).ti.	EPO; JPO;	23:02
		•	DERWENT;	
-]	89	(wafer\$1 with thin\$3 with (divid\$3 or	IBM_TDB USPAT;	2004/03/18
l		separat\$3 or dic\$3)).ti.	EPO; JPO;	23:15
		• •	DERWENT;	
			IBM_TDB	

Page 3

_	153	(wafer\$1 with (thinned or thinning)).ti.	USPAT; EPO; JPO; DERWENT;	2004/03/18 23:31
			IBM_TDB	
-	42		USPAT;	2004/03/18
		and (dic\$3 or divid\$3 or separat\$3)	EPO; JPO;	23:31
			DERWENT; IBM TDB	
_	30	(thinned with chip) and ("smart card" or	USPAT;	2004/03/18
		"smart cards")	EPO; JPO;	23:29
			DERWENT;	
			IBM_TDB	
_	12	(thinned near3 (chip\$1 or die\$1)) and	USPAT;	2004/03/18
		("smart card" or "smart cards")	EPO; JPO; DERWENT;	23:28
			IBM TDB	
-	32	"thinned chip" or "thinned chips"	USPAT;	2004/03/18
		-	EPO; JPO;	23:30
			DERWENT;	
_	0	(vafor¢1 vith (thinned on thinning)) ti	IBM_TDB	2004/02/10
		<pre>(wafer\$1 with (thinned or thinning)).ti. and (dic\$3 or divid\$3 or separat\$3) and</pre>	USPAT; EPO; JPO;	2004/03/18
		(smart with card\$1)	DERWENT;	23.31
			IBM TDB	
-	4	(wafer\$1 with (thinned or thinning)).ti.	USPAT;	2004/03/18
		and (smart with card\$1)	EPO; JPO;	23:32
			DERWENT;	
1 -	2	5192682.pn,.	IBM_TDB USPAT;	2004/03/18
]		EPO; JPO;	23:32
			DERWENT;	23.32
1			IBM_TDB	
-	9	5192682.URPN.	USPAT	2004/03/18
	26	"221470"	IICDAM -	23:33
	20	2213/0	USPAT; US-PGPUB;	2004/05/06
			EPO; JPO;	22.42
l			DERWENT;	
		#0000 #70#	IBM_TDB	
-	13	"2221470"	USPAT;	2004/05/06
			US-PGPUB; EPO; JPO;	22:42
			DERWENT;	
			IBM TDB	
-	. 41	5110388.URPN.	USPĀT	2004/05/06
_	1.5			22:57
_	15	"4433846"	USPAT;	2004/05/07
			US-PGPUB; EPO; JPO;	09:50
			DERWENT;	
			IBM_TDB	
-	40	"smart card" and (thin\$4 near2 chip\$1)	USPAT;	2004/05/07
			US-PGPUB;	10:07
			EPO; JPO;	
			DERWENT; IBM TDB	
-	19	card\$1 with (thinned with chip\$1)	USPAT;	2004/05/07
		* ' '	US-PGPUB;	11:03
			EPO; JPO;	
			DERWENT;	
_	3796	miyamoto and hitachi	IBM_TDB USPAT;	2004/05/07
	3,30		US-PGPUB;	11:03
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	23	(miyamoto and hitachi) and thinned	USPAT;	2004/05/07
			US-PGPUB; EPO; JPO;	11:07
			DERWENT;	
			IBM TDB	

-	6	"6224095"	USPAT; US-PGPUB; EPO; JPO;	2004/05/07 11:05
			DERWENT; IBM_TDB	
-	10	"603514"	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/07
_	3	6342434.URPN.	IBM_TDB USPAT	2004/05/07
-	7	("3861978" "4339297" "5155068" "5238876" "5268065" "5877034"	USPAT	14:53 2004/05/07 14:55
_	45	"5897337").PN. 5155068.URPN.	USPAT	2004/05/07
_	9	("smart card" or "smart cards") and (lacquer\$3 with protect\$3)	USPAT	2004/05/10 11:36
-	16	lacquer\$3 with protect\$3 with chip\$1	USPAT	2004/05/10 10:50
_	37	6193163.pn.	USPAT	2004/05/10
	31	("4889980" "4890197" "4931853" "4990759" "4997791" "5018051" "5048179" "5121294" "5134773" "5173840" "5184209" "5192682" "5208450" "5232532" "5244840"	USPAT	2004/05/10
		"5250341" "5335145" "5346576" "5387306" "5480842" "5510074" "5585618" "5671525" "5725819" "5837992" "5852289" "5876536" "5952713" "5955021" "5969951" "5996897" "6019284" "6025054" "6036099" "6036797" "6066231"		
-	290	"6073856").PN. ("smart card" or "smart cards") and (chip\$1 with surface)	USPAT	2004/05/10
-	13	("smart card" or "smart cards") and (chip\$1 with surface with flush)	USPAT	11:36 2004/05/10 11:39
_	5 	("smart card" or "smart cards") and (press\$3 with chip\$1 with surface with flush)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/10 11:44
-	35	("smart card" or "smart cards") and (press\$3 with chip\$1 with surface)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/10 13:20
-	2	"9852772 "	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/10 11:56
-	3	"19617621"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/10 11:57
_	5	provost and solaic	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/10 13:20
-	1	"1981111"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 14:09

-	3	"1981212"	USPAT;	2004/05/10
			US-PGPUB;	14:09
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
-	2	stromberg and wafer	USPAT	2004/05/10
				14:10
_	9	stromberg and wafer	USPAT;	2004/05/10
			US-PGPUB;	14:10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	658	(dissolv\$3 with adhesive) and (wafer\$1 or	USPAT	2004/05/10
		semiconductor\$1)		14:14
-	298	(dissolv\$3 near2 adhesive) and (wafer\$1	USPAT	2004/05/10
		or semiconductor\$1)		14:14
-	110	(dissolv\$3 with adhesive) and (wafer\$1 or	USPAT	2004/05/10
		semiconductor\$1) and (dic\$3)		14:14
-	74	(dissolv\$3 with adhesive) and (wafer\$1 or	USPAT	2004/05/10
	[']	semiconductor\$1) and (dic\$3) and thin\$4	JULIA	14:14
_	6	("4722130" "5110388" "5118567"	USPAT	2004/05/10
		"5762744" "5888883" "6558975").PN.	OSEAT.	16:02
l -	34	(US-5762744-\$ or US-4878991-\$ or	USPAT;	2004/05/10
	"	US-6046073-\$ or US-5268065-\$ or	US-PGPUB;	16:03
		US-6554193-\$ or US-6193163-\$ or	EPO;	16:03
		US-5155068-\$ or US-4511796-\$ or	DERWENT	
		US-5192682-\$ or US-6105873-\$ or	DERWENT	
		US-5677524-\$ or US-4701600-\$ or		
		US-5122481-\$ or US-5110388-\$ or		
		US-6297076-\$ or US-6007920-\$ or		į
1		US-5882956-\$ or US-5411921-\$ or		
		US-6642127-\$ or US-6342434-\$ or		l
		US-6013534-\$ or US-6412701-\$ or		
		US-5786988-\$ or US-6656819-\$ or		
		US-5994205-\$).did. or (US-20020134842-\$		
		or US-20020069952-\$ or		
		US-20010040186-\$).did. or (EP-824301-\$ or		
		WO-9948137-\$ or WO-9721243-\$ or		
		FR-2780534-\$).did. or (EP-824301-\$ or		
	_	DE-19601391-\$).did.		
-	1	(US-3152939-\$).did.	USOCR	2004/05/10
	_	//**		16:03
-	0	((US-5762744-\$ or US-4878991-\$ or	USPAT;	2004/05/10
		US-6046073-\$ or US-5268065-\$ or	US-PGPUB;	16:03
		US-6554193-\$ or US-6193163-\$ or	EPO;	
ĺ		US-5155068-\$ or US-4511796-\$ or	DERWENT	
	İ	US-5192682-\$ or US-6105873-\$ or		
		US-5677524-\$ or US-4701600-\$ or		
		US-5122481-\$ or US-5110388-\$ or		
	l	US-6297076-\$ or US-6007920-\$ or		
	1	US-5882956-\$ or US-5411921-\$ or		
		US-6642127-\$ or US-6342434-\$ or		İ
		US-6013534-\$ or US-6412701-\$ or		
		US-5786988-\$ or US-6656819-\$ or		
	İ	US-5994205-\$).did. or (US-20020134842-\$		
		or US-20020069952-\$ or		,
		US-20010040186-\$).did. or (EP-824301-\$ or		
		WO-9948137-\$ or WO-9721243-\$ or		
		FR-2780534-\$).did. or (EP-824301-\$ or		
		DE-19601391-\$).did.) and thin44		
		T/ T/ WITH CITTITI		

· · · · · · · · · · · · · · · · · · ·	7			
_	26	1 (USPAT;	2004/05/10
		US-6046073-\$ or US-5268065-\$ or US-6554193-\$ or US-6193163-\$ or	US-PGPUB;	16:03
		US-5155068-\$ or US-4511796-\$ or	EPO;	
		US-5192682-\$ or US-6105873-\$ or	DERWENT	
	1	US-5677524-\$ or US-4701600-\$ or		
		US-5122481-\$ or US-5110388-\$ or		
		US-6297076-\$ or US-6007920-\$ or		
		US-5882956-\$ or US-5411921-\$ or		
		US-6642127-\$ or US-6342434-\$ or		
i		US-6013534-\$ or US-6412701-\$ or		
		US-5786988-\$ or US-6656819-\$ or		
		US-5994205-\$).did. or (US-20020134842-\$		
		or US-20020069952-\$ or		1
		US-20010040186-\$).did. or (EP-824301-\$ or		1
		WO-9948137-\$ or WO-9721243-\$ or		
		FR-2780534-\$).did. or (EP-824301-\$ or		1
		DE-19601391-\$).did.) and thin\$4		
-	26		USPAT;	2004/05/10
		US-6046073-\$ or US-5268065-\$ or	US-PGPUB;	16:20
1		US-6554193-\$ or US-6193163-\$ or	EPO;	
		US-5155068-\$ or US-4511796-\$ or	DERWENT	
		US-5192682-\$ or US-6105873-\$ or	1	
		US-5677524-\$ or US-4701600-\$ or		
		US-5122481-\$ or US-5110388-\$ or		
	1	US-6297076-\$ or US-6007920-\$ or	1	
		US-5882956-\$ or US-5411921-\$ or		
		US-6642127-\$ or US-6342434-\$ or		
		US-6013534-\$ or US-6412701-\$ or		
		US-5786988-\$ or US-6656819-\$ or		
		US-5994205-\$).did. or (US-20020134842-\$	1	
	İ	or US-20020069952-\$ or		
1		US-20010040186-\$).did. or (EP-824301-\$ or WO-9948137-\$ or WO-9721243-\$ or		
		FR-2780534-\$).did. or (EP-824301-\$ or		
		DE-19601391-\$).did.) and thin\$4		
	6	("4722130" "5110388" "5118567"	USPAT	2004/05/10
	1	"5762744" "5888883" "6558975").PN.	OBERT	2004/05/10
-	11	"475259"	USPAT;	2004/05/10
			US-PGPUB;	16:26
1			EPO;	
			DERWENT	
-	6	("4722130" "5110388" "5118567"	USPAT	2004/05/10
] ,	"5762744" "58888883" "6558975").PN.		16:24
_	0	6656819.URPN.	USPAT	2004/05/10
	[_ [W0005040W		16:25
-	3	"9925019"	USPAT;	2004/05/10
[US-PGPUB;	16:27
			EPO; JPO;	
	1		DERWENT;]
! _	5	"63164336"	IBM_TDB	
	5	02104330	USPAT;	2004/05/11
1			US-PGPUB;	10:25
			EPO; JPO;]
]			DERWENT;	
-	2118	lintec.as.	<pre>IBM_TDB USPAT;</pre>	2004/05/11
	-110		US-PGPUB;	2004/05/11
		·	EPO; JPO;	11.54
			DERWENT;]
			IBM TDB	
-	3	"63148655"	USPAT;	2004/05/11
			US-PGPUB;	10:26
			EPO; JPO;	
	[DERWENT;	
			IBM TDB	
-	492	156/344.ccls. and 156/584.ccls.	USPAT	2004/05/11
				11:38
-	112	(156/344.ccls. and 156/584.ccls.) and	USPAT	2004/05/11
L	ll	(semiconductor\$1 or wafer\$1)		11:38

····				
-	414	lintec.as. and (semiconductor\$1 or	USPAT;	2004/05/11
		wafer\$1)	US-PGPUB;	11:52
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	203		USPAT;	2004/05/11
ļ		and (grind\$3 or thin\$4 or polish\$3)	US-PGPUB;	11:53
			EPO; JPO;	
			DERWENT;	i
			IBM TDB	
_	76	lintec and (semiconductor\$1 or wafer\$1)	USPAT;	2004/05/11
		and (grind\$3 or thin\$4 or polish\$3) and	US-PGPUB;	12:03
		(die or dice)	EPO; JPO;	
		,	DERWENT;	
İ			IBM TDB	
_	6	("4722130" "5762744" "5989982"	USPAT	2004/05/11
		"6054372" "6083811" "6297131").PN.	ODEAT	12:00
_	1148	GIESECKE and DEVRIENT	HCDAT.	1
	1140	GIESECKE AND DEVKIENT	USPAT;	2004/05/11 12:03
			US-PGPUB;	12:03
			EPO; JPO;	
			DERWENT;	
		(CIRCICIE - A PRINTED)	IBM_TDB	0004/05/55
_	22	,,	USPAT;	2004/05/11
		semiconductor\$1	US-PGPUB;	12:05
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	31	(GIESECKE and DEVRIENT) and	USPĀT;	2004/05/11
		(semiconductor\$1 or wafer\$1)	US-PGPUB;	15:05
			EPO; JPO;	
			DERWENT;	
		·	IBM TDB	
-	10	"624341"	USPAT;	2004/05/11
			US-PGPUB;	12:12
			EPO; JPO;	12.12
			DERWENT;	
			IBM TDB	
<u>-</u>	5	"5912185"	USPAT;	2004/05/11
:	,	3912103	US-PGPUB;	12:13
			•	12:13
			EPO; JPO;	
			DERWENT;	[
	_ :	#0011EC#	IBM_TDB	0004/05/11
-	7	"981156"	USPAT;	2004/05/11
		•	US-PGPUB;	12:14
			EPO; JPO;	
			DERWENT;	1
			IBM_TDB	1
-	3	"6465330"	USPAT;	2004/05/11
			US-PGPUB;	12:14
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	5	("4756968" "5714029" "5888883"	USPAT	2004/05/11
		"6126772" "6312800").PN.]	12:15
-	33	4756968.URPN.	USPAT	2004/05/11
				12:16
1-	1	6083811.pn.	USPAT	2004/05/11
		,	Join	12:38
_	48	"dicing film" with adhesive	IISDAT.	2004/05/11
	10	arching trum with aunestive	USPAT;	1
			US-PGPUB;	14:37
			EPO; JPO;	[
		•	DERWENT;	
	_	#1.0021.000#	IBM_TDB	
-	5	"10231602"	USPAT;	2004/05/11
			US-PGPUB;	14:41
			EPO; JPO;	
			DERWENT;	ļ
			IBM_TDB	
			 	<u> </u>

-	23789	((wafer\$1 or semiconductor\$1) with	USPAT;	2004/05/11
		(grind\$3 or thin\$4)).ti.	US-PGPUB;	14:42
			EPO; JPO;	
			DERWENT;	
	0.4.6		IBM_TDB	
-	946	((wafer\$1 or semiconductor\$1) with	USPAT	2004/05/11
		(grind\$3 or thin\$4)).ti.	l	14:42
-	93	((wafer\$1 or semiconductor\$1) with	USPAT	2004/05/11
•	10206	(grinding or thinning or thinned)).ti.		15:02
-	10306	"19921230"	USPAT;	2004/05/11
	}		US-PGPUB;	15:03
			EPO; JPO;	
			DERWENT;	
1_	1	"19921230" and haghiri	<pre>IBM_TDB USPAT;</pre>	2004/05/11
-	*	19921230 and nagniff	I .	15:05
			US-PGPUB; EPO; JPO;	15:05
			DERWENT;	
İ			IBM TDB	
_	591	haghiri	USPAT;	2004/05/11
		Haghiii	US-PGPUB;	15:05
	1		EPO; JPO;	13.03
	1	·	DERWENT;	'
			IBM TDB	
_	86	(GIESECKE and DEVRIENT) and haghiri	USPAT;	2004/05/11
		(Oldonolia dila bavillari) dila liagilla	US-PGPUB;	15:05
1			EPO; JPO;	10.00
			DERWENT;	1
			IBM TDB	
_	6	(GIESECKE and DEVRIENT) and haghiri and	USPAT;	2004/05/11
		(semiconductor\$1 or wafer\$1)	US-PGPUB;	15:05
		(· · · · · · · · · · · · · · · · · · ·	EPO; JPO;	13.33
			DERWENT;	
			IBM TDB	
_	10311	"19921230"	USPAT;	2004/08/11
			US-PGPUB;	20:49
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	"19921230".pn.	USPĀT;	2004/08/11
			US-PGPUB;	20:49
1			EPO; JPO;	
			DERWENT;	
	}		IBM_TDB	
-	6	"19811115"	USPAT	2004/08/11
		W4004445#		21:07
-	1521	"19811115"	USPAT;	2004/08/11
			US-PGPUB;	21:07
			EPO; JPO;	
			DERWENT;	
		#1001111F#	IBM_TDB	
-	2	"19811115".pn.	USPAT;	2004/08/11
			US-PGPUB;	21:07
			EPO; JPO;	
1			DERWENT;	
_		#10012120#	IBM_TDB	0004/00/07
_	0	"19812120"	USPAT	2004/08/11
l _	0	"10912120" nn	HGDAG	21:32
-		"19812120".pn.	USPAT;	2004/08/11
			US-PGPUB;	21:32
			EPO; JPO;	
			DERWENT;	
_	ol	"19812120".pn.	<pre>IBM_TDB USPAT;</pre>	2004/09/11
		12012120 · hii:	ľ.	2004/08/11
	l i		US-PGPUB; EPO; JPO;	21:33
			DERWENT;	
			IBM TDB	
L	L		TD11_1DD	l

[-	3542	156/584 or 156/344	USPAT;	2004/08/11
	3342	100,001 01 100,011	US-PGPUB;	21:39
			EPO; JPO;	21.39
			DERWENT;	
			IBM TDB	
_	573	(156/584 or 156/344) and (semiconductor\$1	USPAT;	2004/00/11
	3/3	or wafer\$1)	1	2004/08/11 21:41
		Of watery)	US-PGPUB;	21:41
			EPO; JPO;	
			DERWENT;	
	222	/156/504 156/344)	IBM_TDB	
-	322	(156/584 or 156/344).ccls. and	USPAT;	2004/08/11
		(semiconductor\$1 or wafer\$1)	US-PGPUB;	21:41
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	56	card\$1.ti. and (chip\$1 with (exterior or	USPAT	2004/08/20
		external\$2) with surface)		20:50
-	20	card\$1.ti. and (chip\$1 with (exterior or	USPAT	2004/08/20
		external\$2) with surface with (circuit\$2		20:50
		or coil))		1
-	10	"824301"	USPAT;	2004/08/20
			US-PGPUB;	20:16
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
-	48	card\$1.ti. and (chip\$1 with (exterior or	USPAT	2004/08/20
		external\$2) with surface) and (circuit\$2		20:57
		or coil)	İ	
-	28	(card\$1.ti. and (chip\$1 with (exterior or	USPAT	2004/08/20
		external\$2) with surface) and (circuit\$2		20:50
		or coil)) not (card\$1.ti. and (chip\$1		
		with (exterior or external\$2) with		
		<pre>surface with (circuit\$2 or coil)))</pre>		
_	24	card\$1.ti. and (chip\$1 with (exterior or	USPAT	2004/08/20
		external\$2) with surface) and ((circuit\$2		20:57
		or coil) with print\$3)		20.07
_	4	"6412701" AND PRINT\$3	USPAT	2004/08/22
İ	-		USIAI	22:14